

#13  
PATENT  
9/3/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

5 Applicant: Kuo-Ming Chen  
Examiner: Nguyen, Dilinh P  
Filing Date: 05/21/2002 Art Unit: 2814  
App. No.: 10/063,880 Docket No.: NAUP0481USA

10 Title: SOLDER PADS FOR IMPROVING RELIABILITY OF A  
PACKAGE

To: Commissioner for Patents  
P.O. Box 1450  
15 Alexandria VA 22313-1450

Subject: Response to the Office action dated 06/04/2003

Dear Sir or Madame:

20

INTRODUCTORY COMMENTS

25 In response to the Office action identified above,  
the above-identified application is to be amended as  
indicated in the following sections. Consideration of  
all amendments is politely requested.

30